

제 24회 한국반도체학술대회  
세션: [TC1-G] Device Physics and Characterization 1



**DFT study on the clean-up mechanism  
of InGaAs(001) native oxides  
in atomic layer deposition**

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## •Introduction

- Oxidation & Fermi-level pinning
- ALD & Self-cleaning

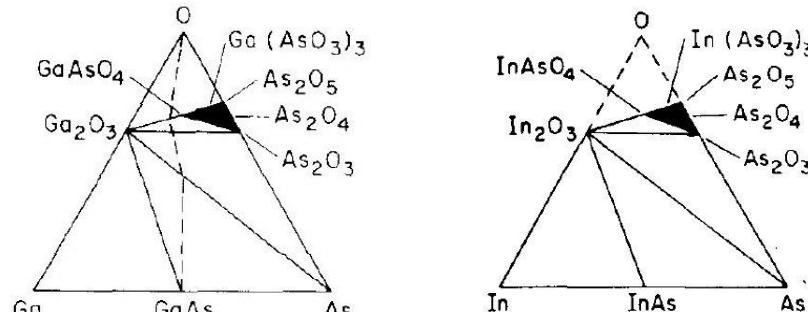
## •Clean-up reaction of native oxides of InAs

- Removal of  $\text{As}_2\text{O}_3$  by pretreatment: thermodynamics
- Removal of  $\text{In}_2\text{O}_3$  by ALD: thermodynamics
- Removal of  $\text{In}_2\text{O}_3$  by ALD: atomic mechanism

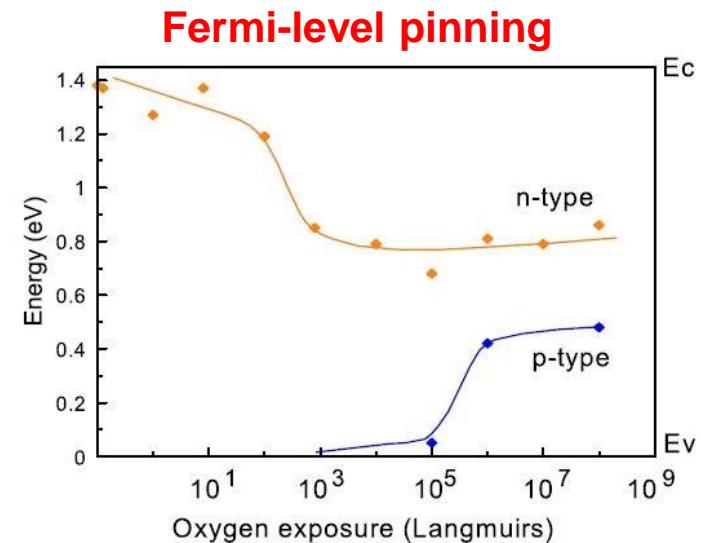
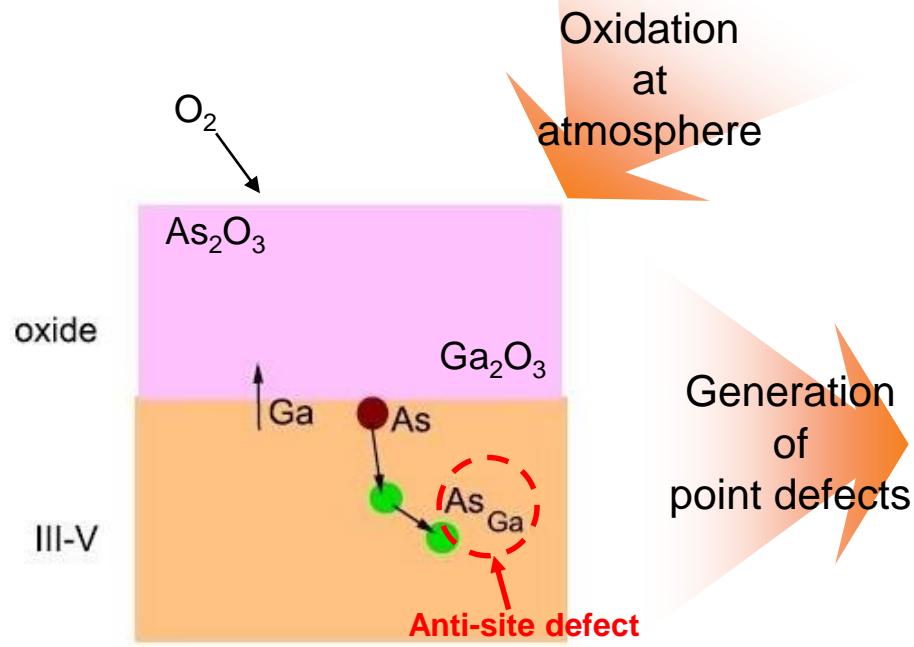
## •Summary

# Native oxides of GaAs & InAs

Ga-As-O & In-As-O ternary phase diagram



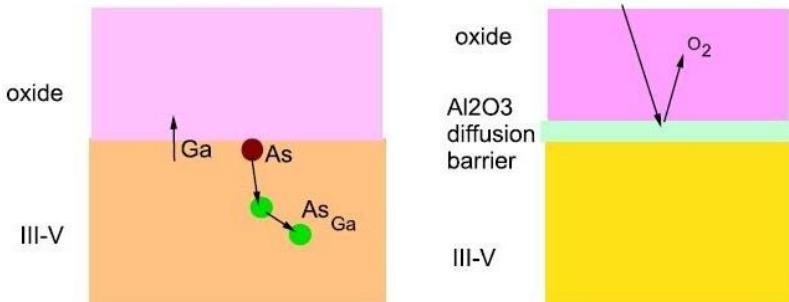
Thin Solid Film, 103, 3 (1983).



Phys. Rev. Lett. 44, 420 (1980).

# Lower $D_{it}$ after high-k ALD

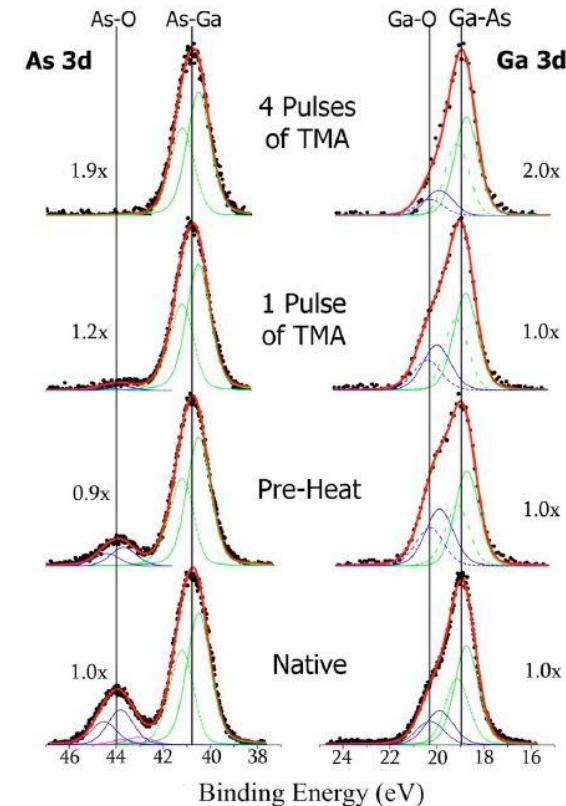
## High-k oxides as diffusion barrier



Materials Science and Engineering R 88, 1 (2015).

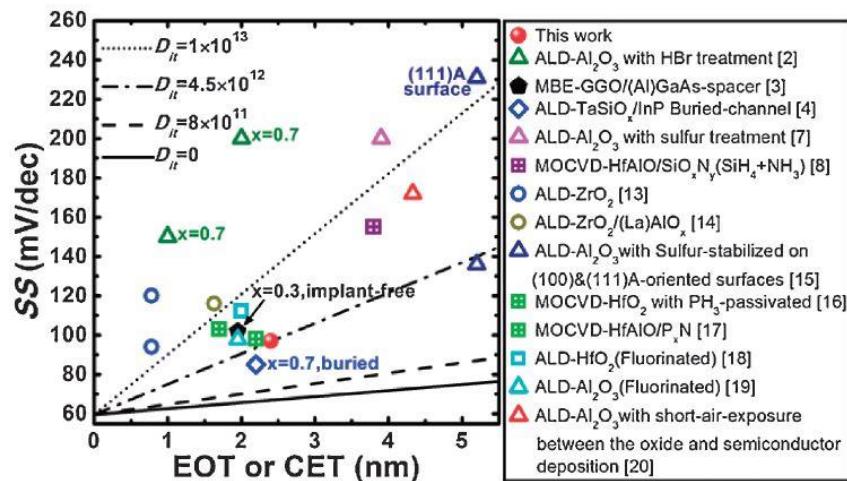
ALD half cycle  
by  
 $\text{Al}(\text{CH}_3)_3$

## Removal of native oxides



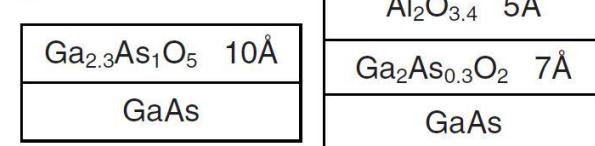
“Self-cleaning”

## Lower $D_{it}$ & better performance



Device characterization

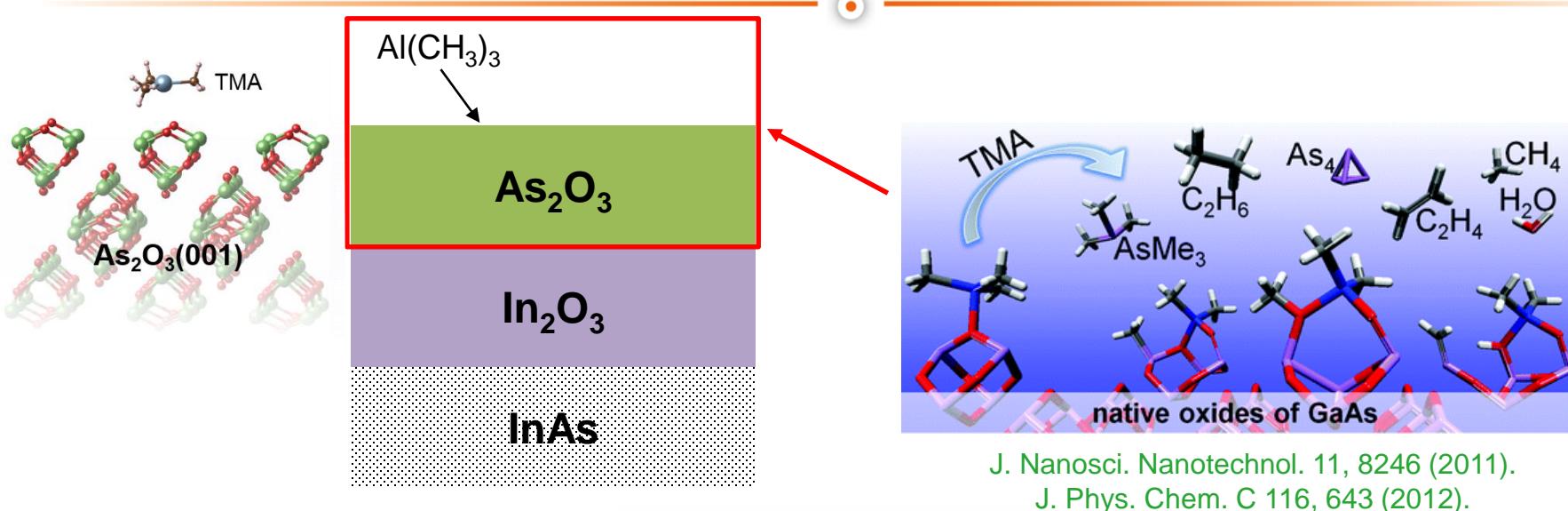
(b)



320 °C preheated      1 TMA pulse exposed

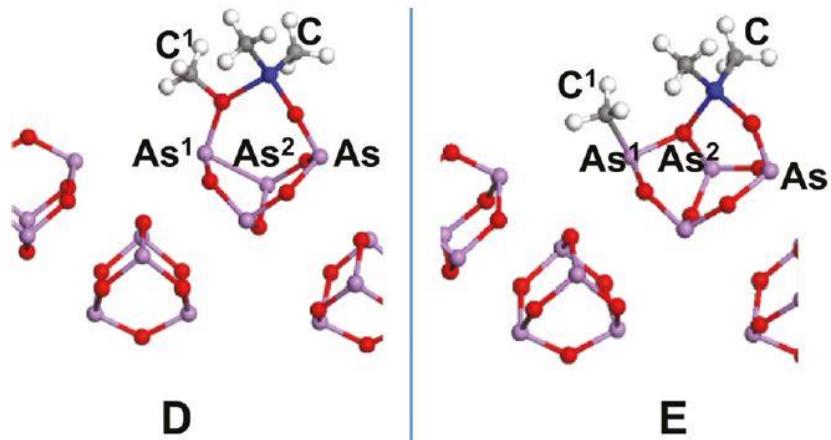
Appl. Phys. Lett. 94, 222108 (2009).

# Modeling of the “self-cleaning”: previous study

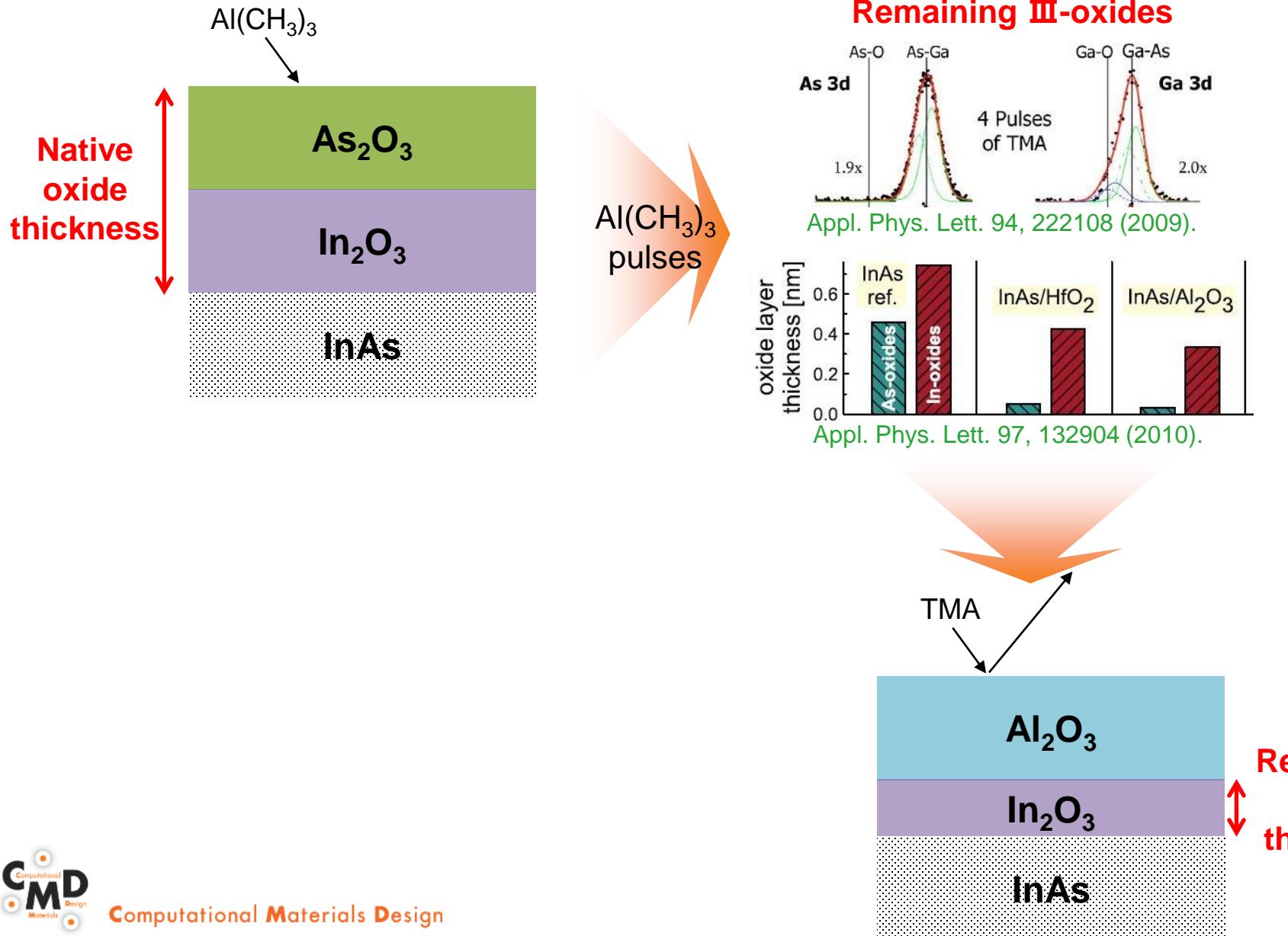


J. Nanosci. Nanotechnol. 11, 8246 (2011).  
J. Phys. Chem. C 116, 643 (2012).

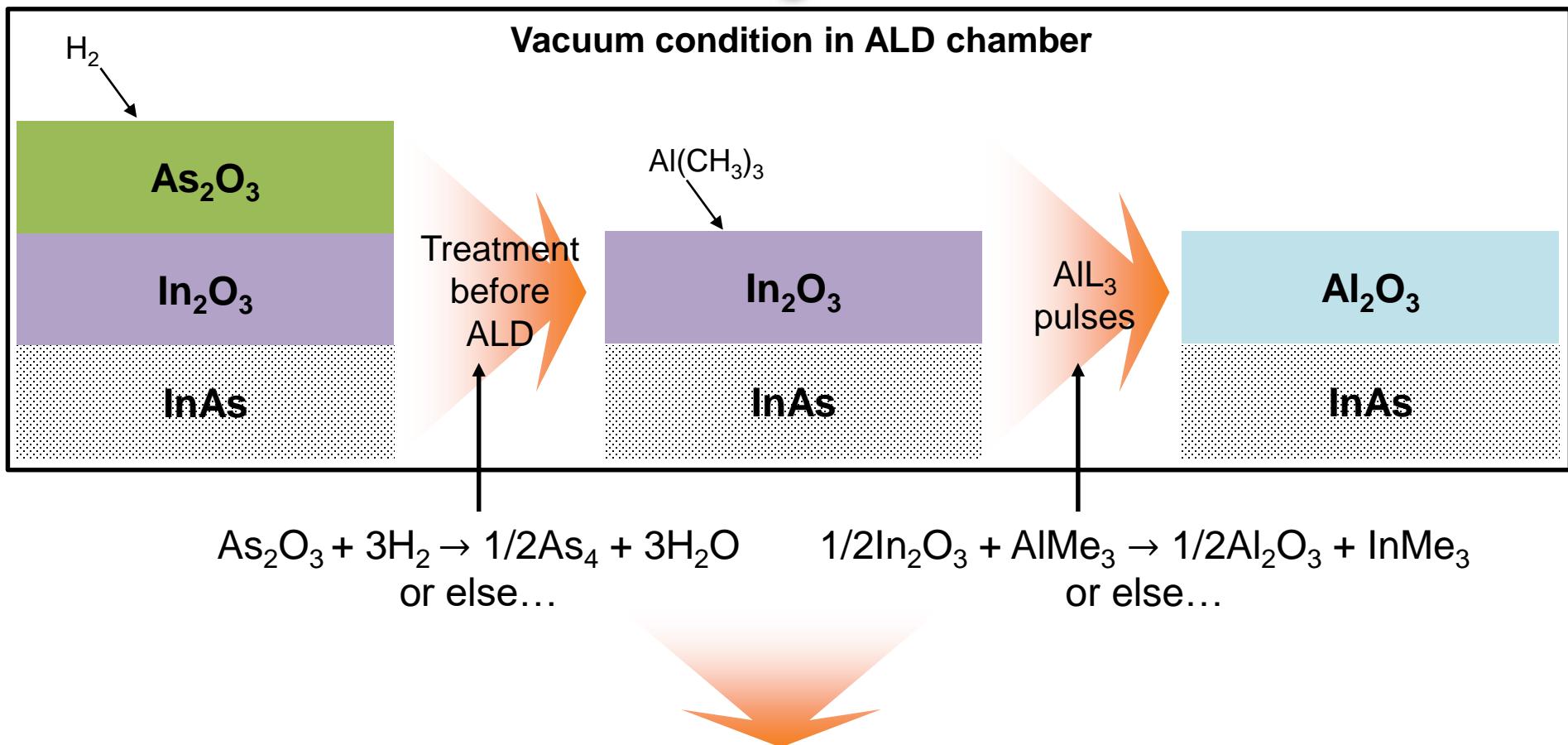
Reaction	$\Delta G_{(b)}^{573.15 K}$	$\Delta E_{(b)}^{0 K}$
(1) $(1/2)\text{As}_2\text{O}_3 + \text{AlMe}_3 \rightarrow (1/2)\text{Al}_2\text{O}_3 + \text{AsMe}_3$	-4.0	-4.4
(2) $(1/2)\text{As}_2\text{O}_3 + \text{AlMe}_3 \rightarrow (1/2)\text{Al}_2\text{O}_3 + (1/4)\text{As}_4 + (3/2)\text{C}_2\text{H}_6$	-5.6	-5.2
(3) $(1/2)\text{As}_2\text{O}_3 + \text{AlMe}_3 \rightarrow (1/2)\text{Al}_2\text{O}_3 + \text{AsH}_3 + (3/2)\text{C}_2\text{H}_4$	-3.6	-2.3
(4) $(1/2)\text{As}_2\text{O}_3 + \text{AlMe}_3 \rightarrow (1/2)\text{Al}_2\text{O}_3 + (1/4)\text{As}_4 + (3/4)\text{C}_2\text{H}_4 + (3/2)\text{CH}_4$	-5.8	-4.5
(5) $\text{As}_2\text{O}_3 + \text{AlMe}_3 \rightarrow (1/2)\text{Al}_2\text{O}_3 + (1/2)\text{As}_4 + (3/2)\text{C}_2\text{H}_4 + (3/2)\text{H}_2\text{O}$	-6.3	-3.1
(6) $4\text{As}_2\text{O}_3 + \text{AlMe}_3 \rightarrow (1/2)\text{Al}_2\text{O}_3 + 2\text{As}_4 + 3\text{CO}_2 + (9/2)\text{H}_2\text{O}$	-15.7	-2.5



# Modeling of the “self-cleaning”: previous study



# Modeling of the “self-cleaning”: this study

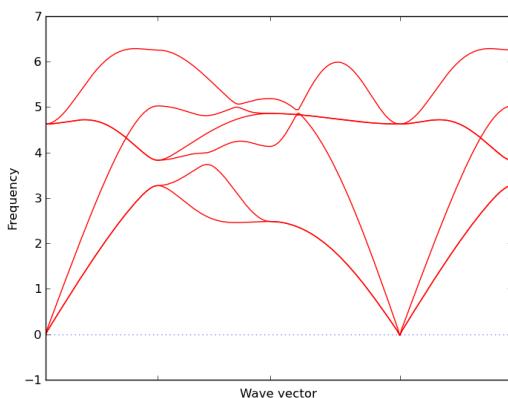
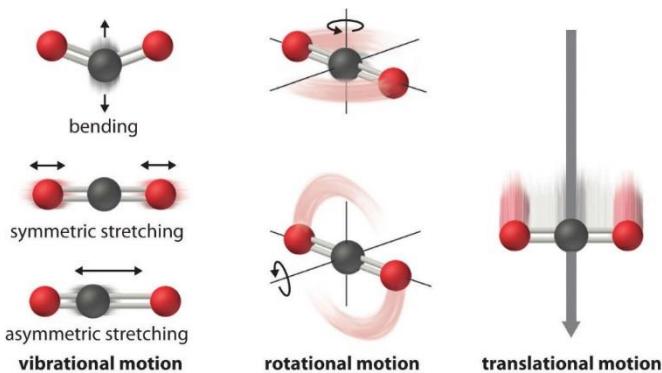


- Possible reaction?  $\Delta G > 0$  or  $\Delta G < 0$
- Then how?? Atomic mechanism

# Calculation methods

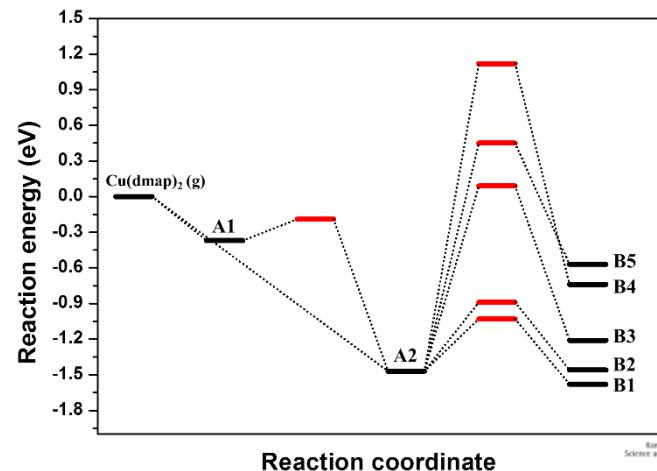
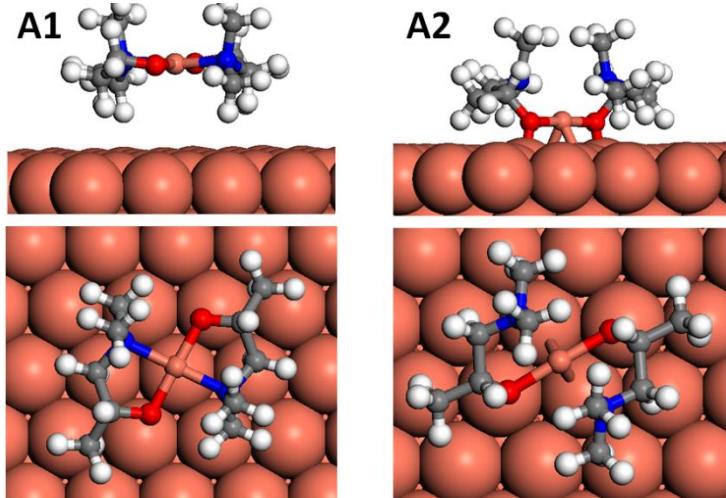
## 1. Bulk thermodynamics

- VASP + PHONOPY
- 500 eV cut-off with PBE functional
- $\mu_{i(gas)}(T, P) = \frac{-k_B T \ln Q_{i(gas)}^{tot} + PV}{N}$ .
- $Q_{i(gas)}^{tot} = \frac{1}{N!} (q^{trans} q^{rot} q^{vib} q^{elec})^N$

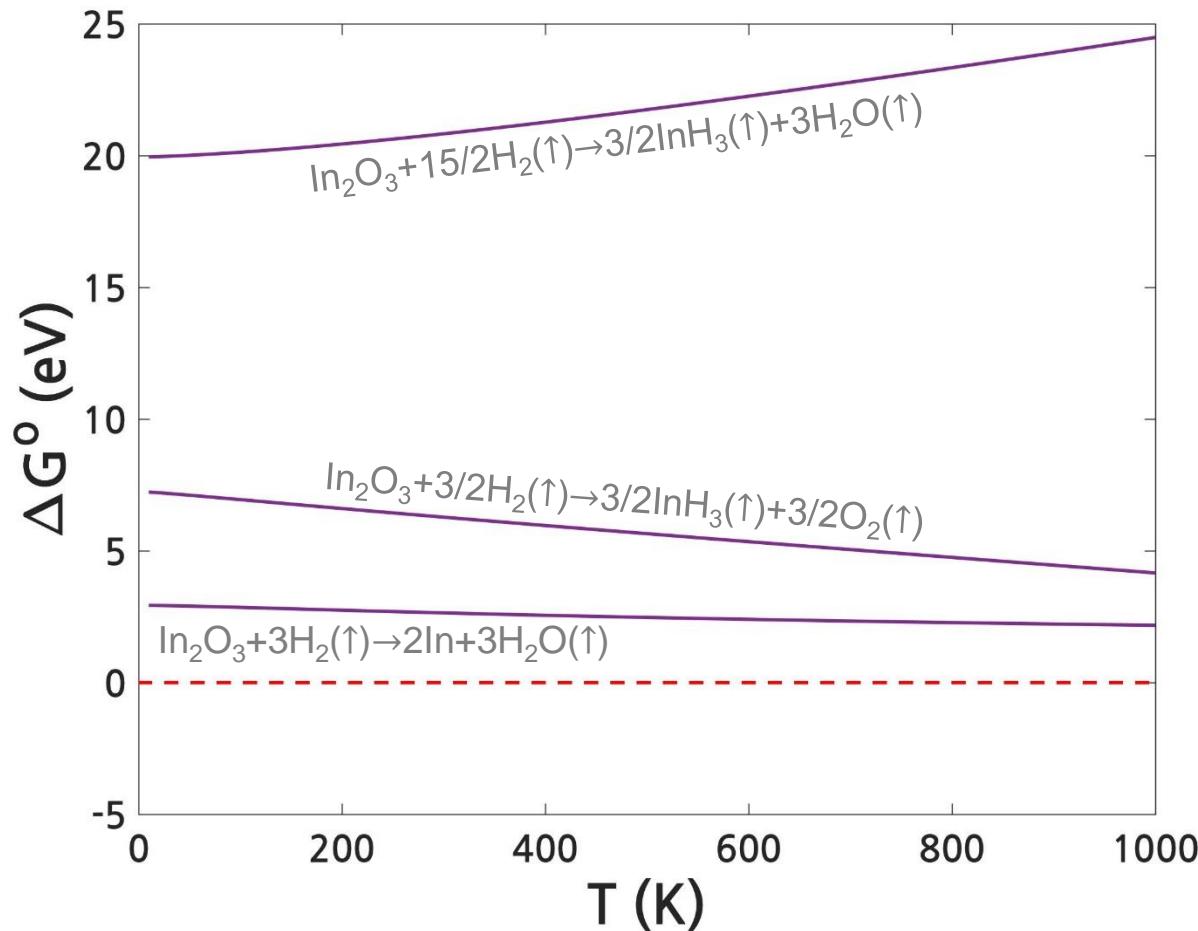
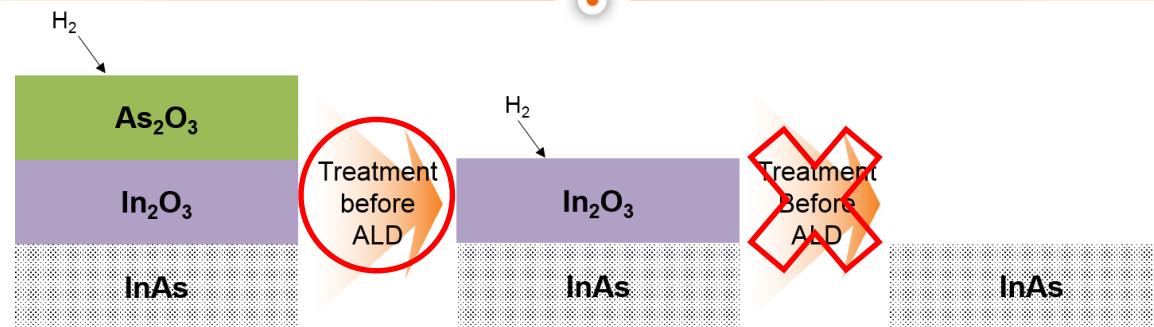


## 2. Atomic mechanism

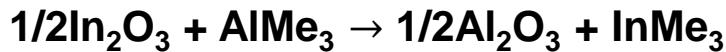
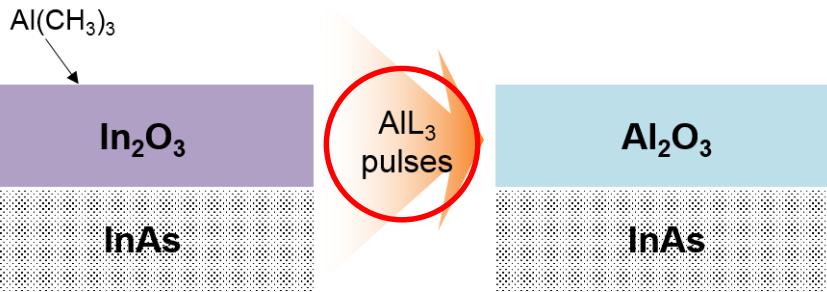
- VASP
- 500 eV cut-off with PBE functional



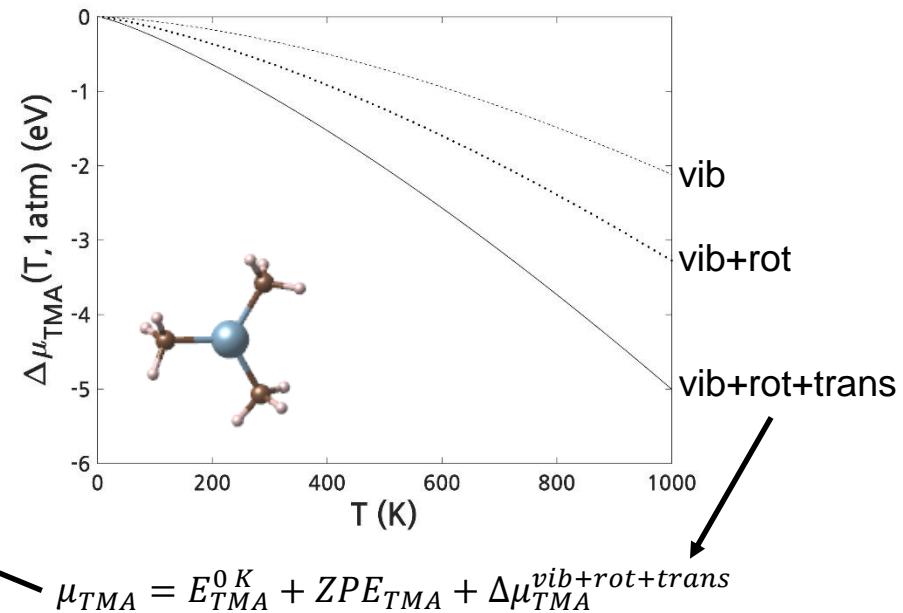
# InAs(001) cleaning: H<sub>2</sub> pretreatment



# InAs(001) cleaning: AIL<sub>3</sub> pulse (L=alkyl)

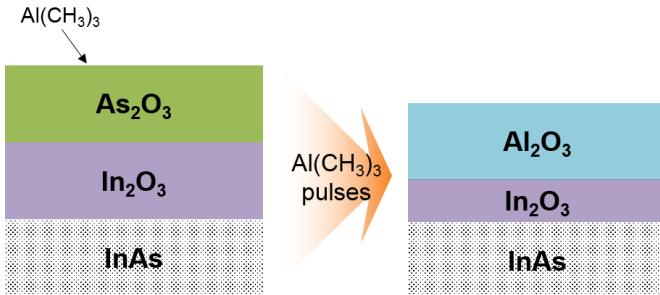


$$\Delta G = \frac{1}{2}\mu_{\text{Al}2\text{O}3} + \mu_{\text{InMe}3} - \frac{1}{2}\mu_{\text{In}2\text{O}3} - \mu_{\text{AlMe}3}$$

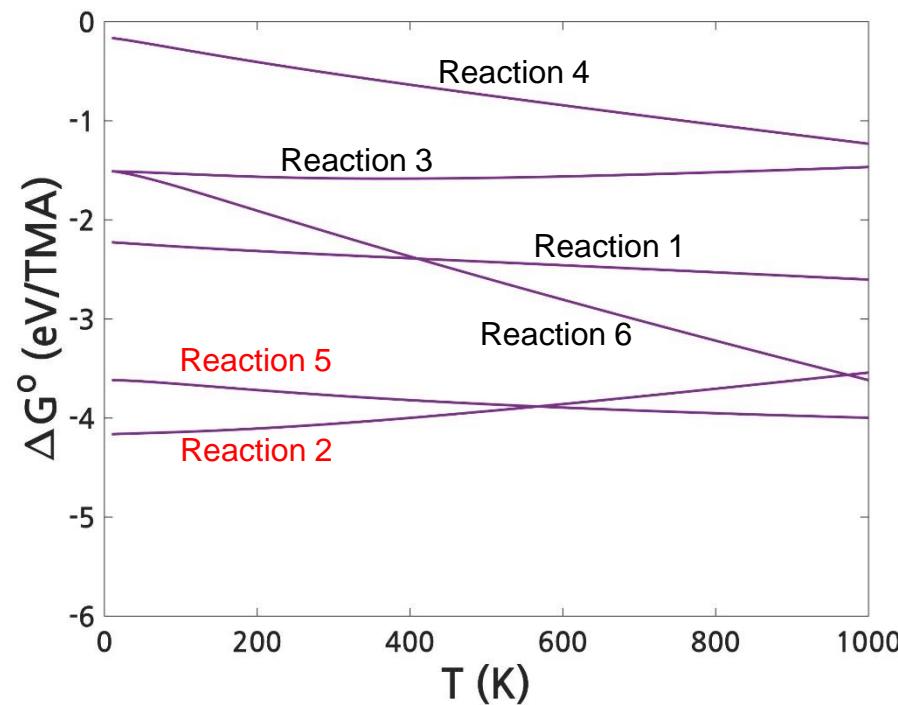
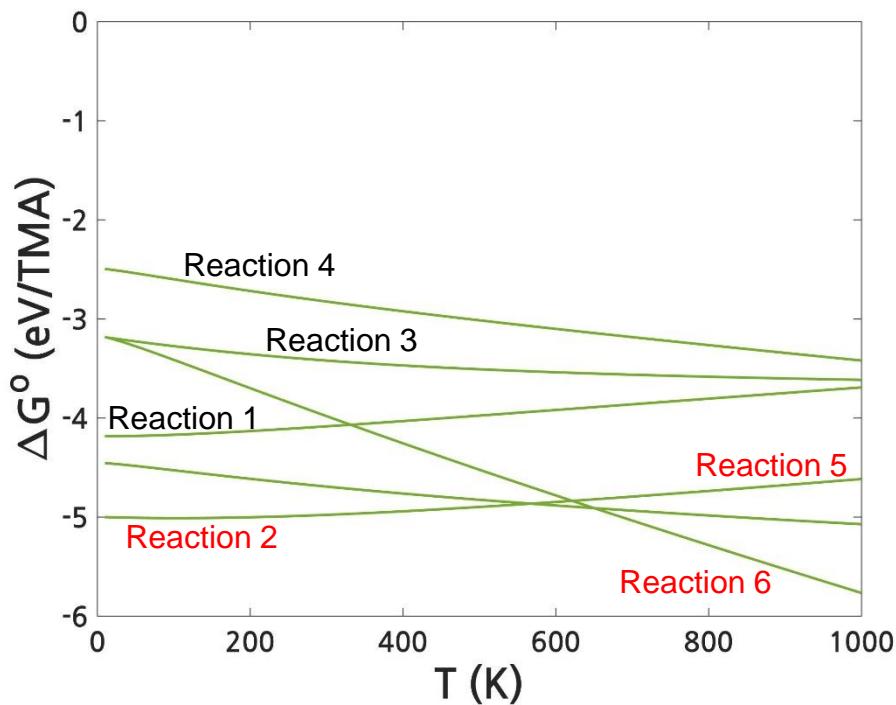
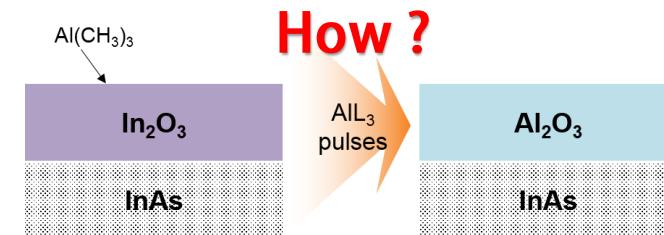


	Reaction	$\Delta G^{573\text{ K}} \text{ (eV)}$
1	$\frac{1}{2}\text{In}_2\text{O}_3 + \text{AlMe}_3 \rightarrow \frac{1}{2}\text{Al}_2\text{O}_3 + \text{InMe}_3$	-2.45
2	$\frac{1}{2}\text{In}_2\text{O}_3 + \text{AlMe}_3 \rightarrow \frac{1}{2}\text{Al}_2\text{O}_3 + \text{In} + \frac{3}{2}\text{C}_2\text{H}_6$	-3.88
3	$\text{In}_2\text{O}_3 + \text{AlMe}_3 \rightarrow \frac{1}{2}\text{Al}_2\text{O}_3 + 2\text{In} + \frac{3}{2}\text{OMe}_2$	-1.57
4	$\frac{1}{2}\text{In}_2\text{O}_3 + \text{AlMe}_3 \rightarrow \frac{1}{2}\text{Al}_2\text{O}_3 + \text{InH}_3 + \frac{3}{2}\text{C}_2\text{H}_4$	-0.82
5	$\frac{1}{2}\text{In}_2\text{O}_3 + \text{AlMe}_3 \rightarrow \frac{1}{2}\text{Al}_2\text{O}_3 + \text{In} + \frac{3}{4}\text{C}_2\text{H}_4 + \frac{3}{2}\text{CH}_4$	-3.89
6	$\text{In}_2\text{O}_3 + \text{AlMe}_3 \rightarrow \frac{1}{2}\text{Al}_2\text{O}_3 + 2\text{In} + \frac{3}{2}\text{C}_2\text{H}_4 + \frac{3}{2}\text{H}_2\text{O}$	-2.74

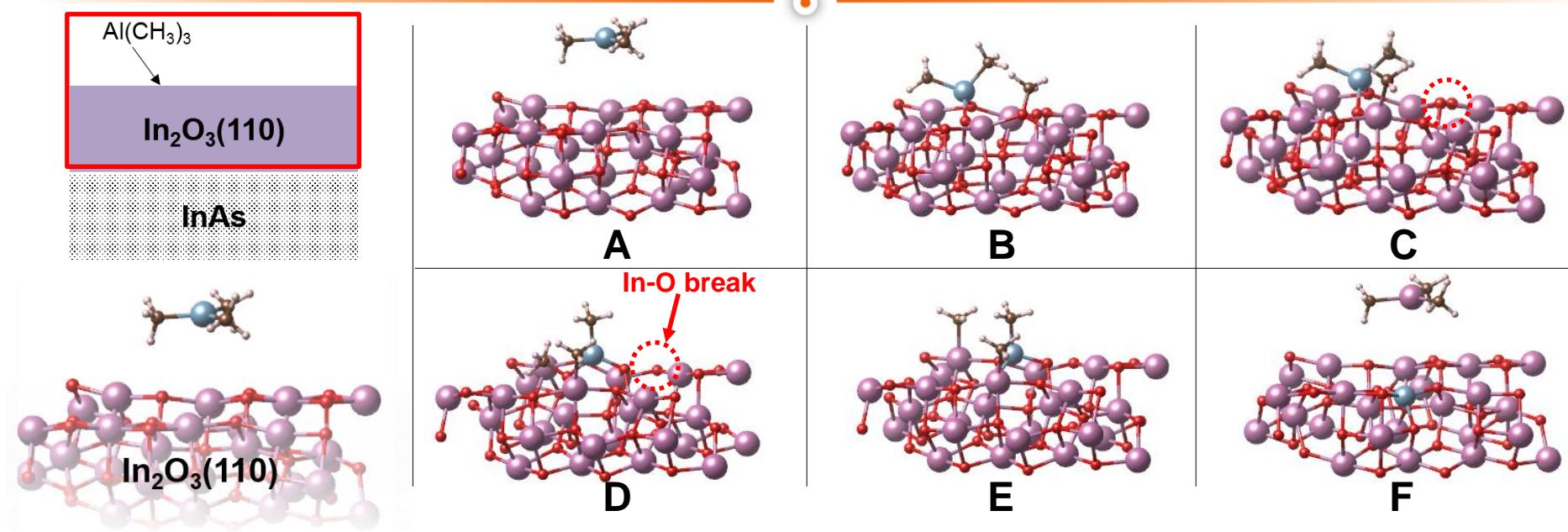
# InAs(001) cleaning: As<sub>2</sub>O<sub>3</sub> vs In<sub>2</sub>O<sub>3</sub>



**VS**

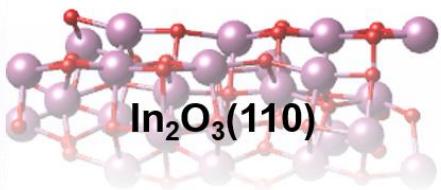


# Atomic mechanism: L-transfer (L=methyl)

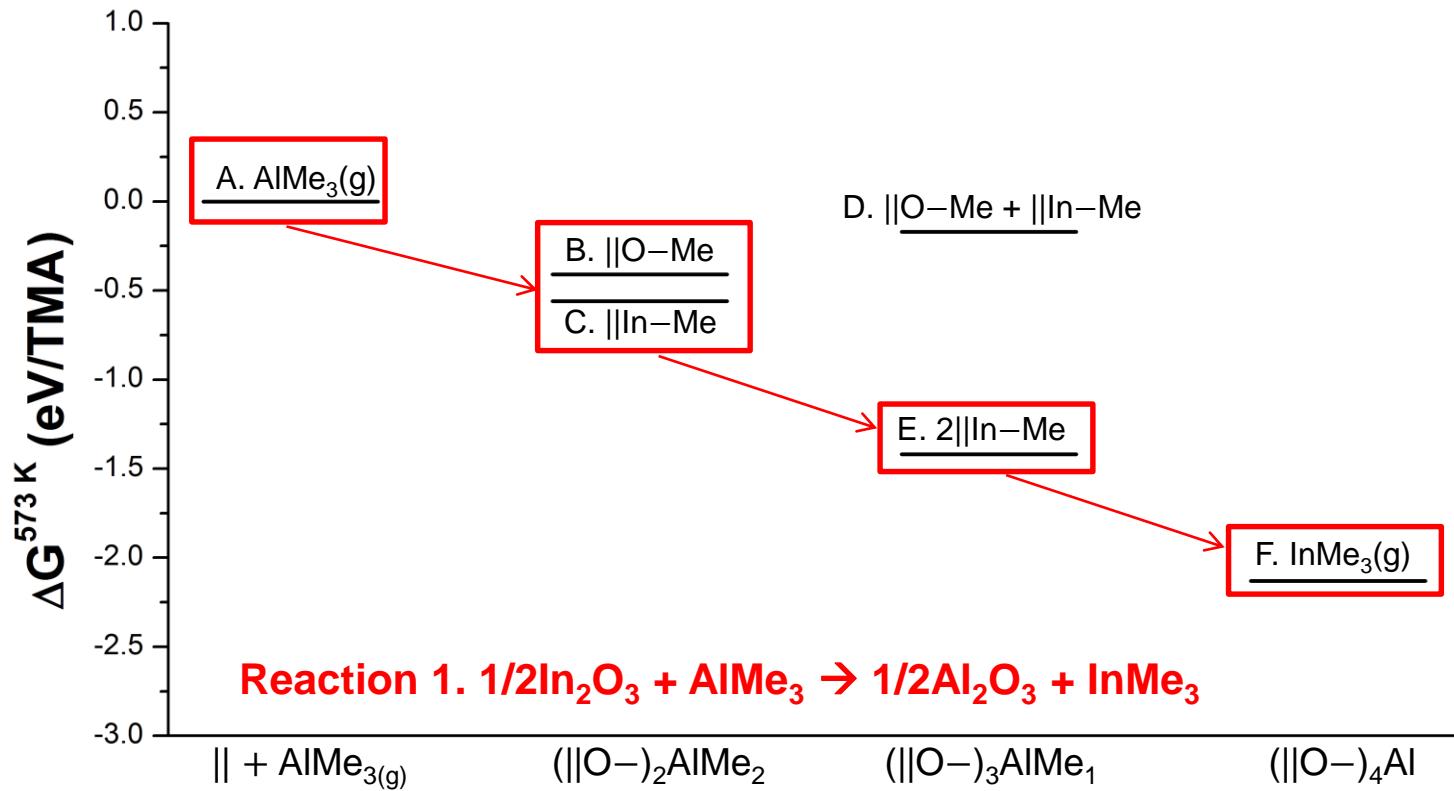


	Products at surface	$\Delta G^{573\text{ K}}$ (eV)
A	$\text{In}_2\text{O}_3(\text{surf}) + \text{AlMe}_3(\text{g})$	0.00
B	$(\text{  O}-)_2\text{AlMe}_2 + \text{  O-Me}$	-0.41
C	$(\text{  O}-)_2\text{AlMe}_2 + \text{  In-Me}$	-0.56
D	$(\text{  O}-)_3\text{AlMe} + \text{  O-Me} + \text{  In-Me}$	-0.17
E	$(\text{  O}-)_3\text{AlMe} + 2 \text{   In-Me}$	-1.42
F	$(\text{  O}-)_4\text{Al} + \text{InMe}_3(\text{g})$	-2.13

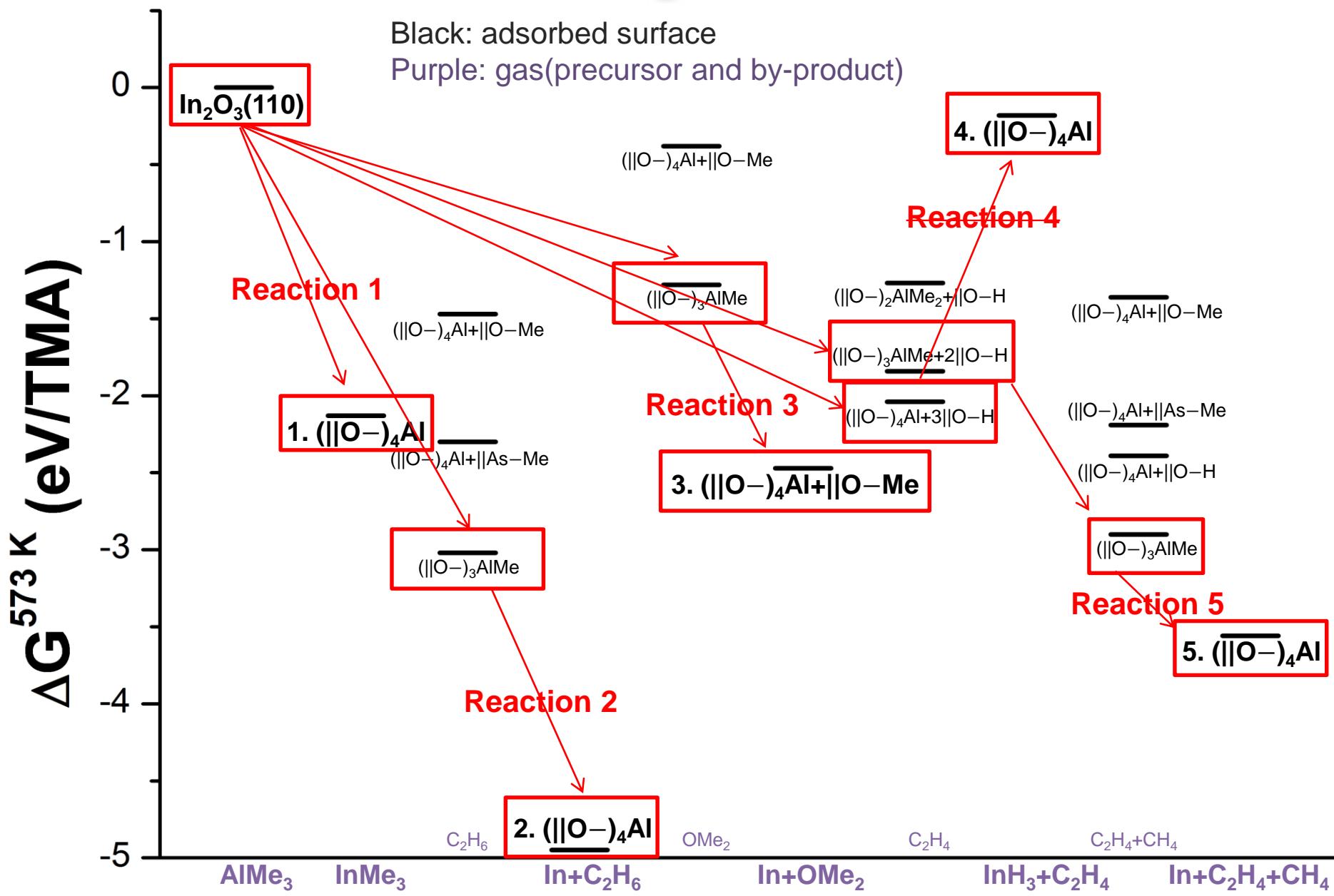
# Atomic mechanism: L-transfer (L=methyl)



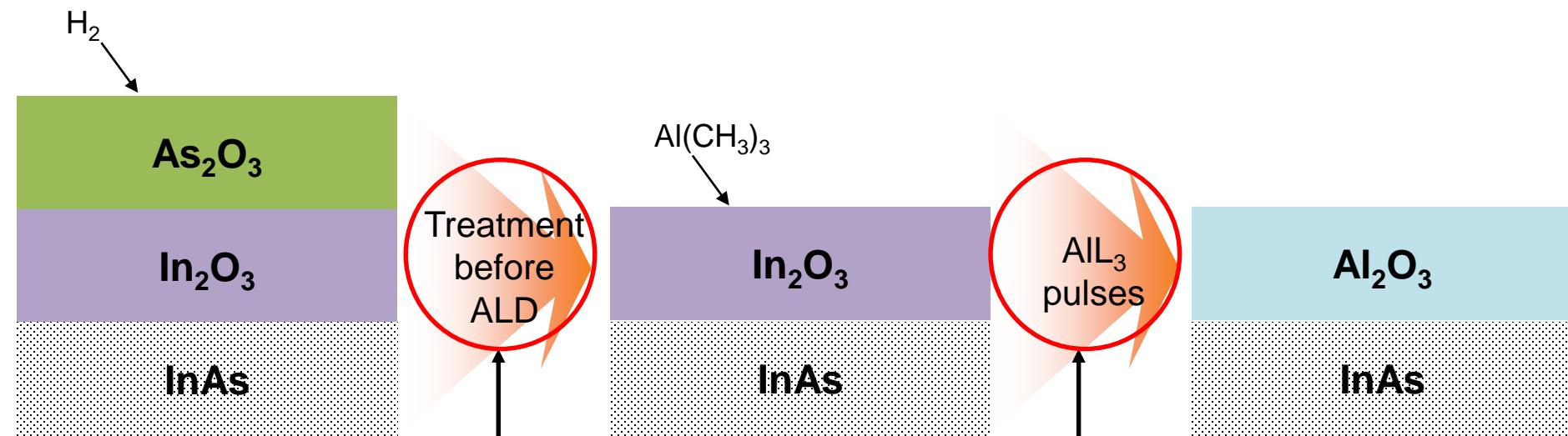
where ||X is a binding site of the surface, X=In or O.



# Atomic mechanism: one TMA on $\text{In}_2\text{O}_3(110)$



# Summary



Most probable path: reaction 2.



Inhibited path: reaction 4.

